



SOT1232-1

plastic flip-chip quad flat package; no leads; 6 terminals;
body 1.1 x 0.7 x 0.37 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON6
Package type industry code	FC-QFN6
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-8-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.65	-	0.7	0.75	mm
E	package width	1.05	-	1.1	1.15	mm
A	seated height	0.34	-	0.37	0.4	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

FC-QFN6: plastic flip-chip quad flat package; no leads; 6 terminals; body 1.1 x 0.7 x 0.37 mm SOT1232-1

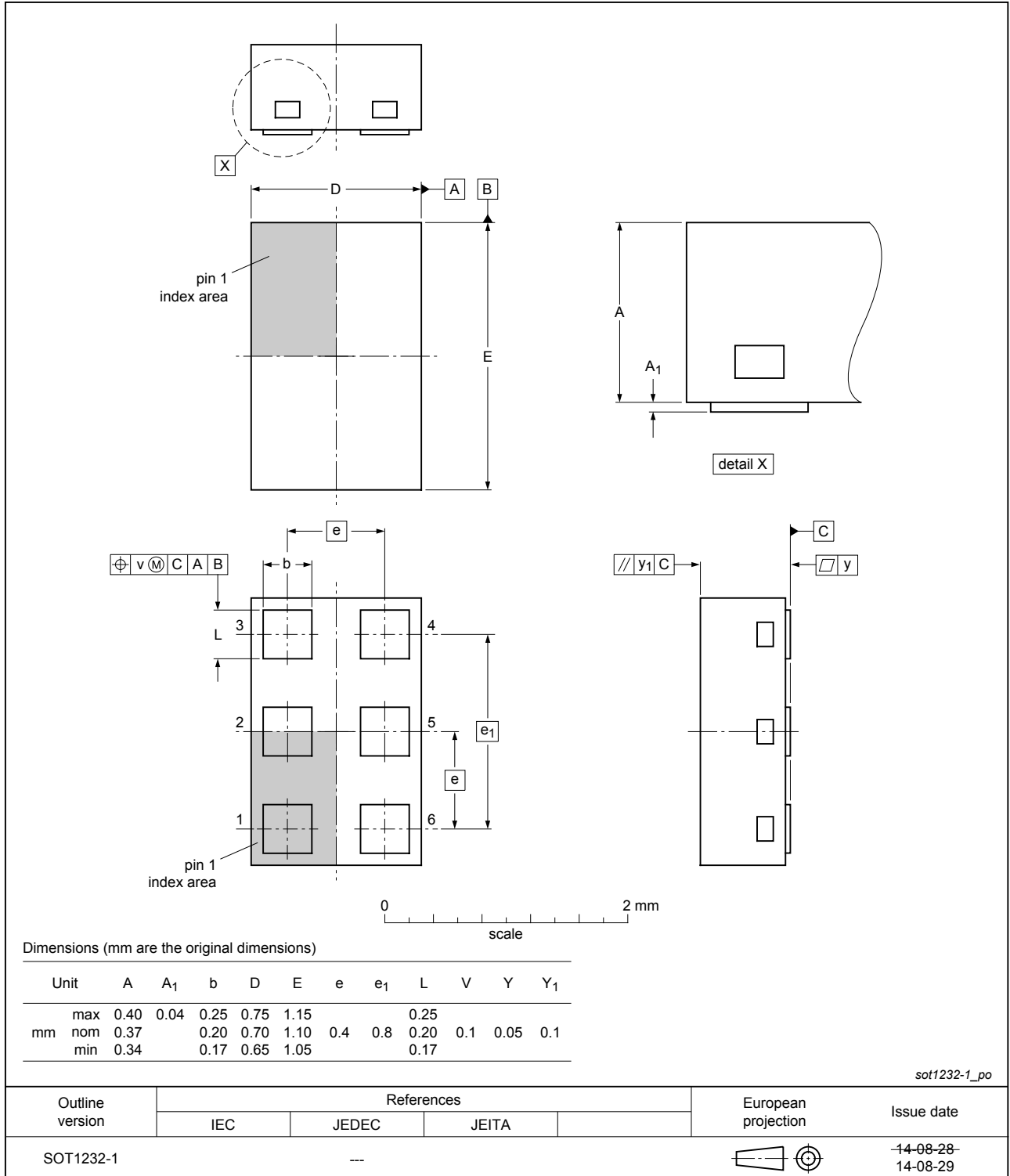


Fig. 1. Package outline FC-QFN6 (SOT1232-1)

3. Legal information

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